



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Gurtej Singh Sandhu et al.
Title: METHOD FOR FORMING A METALLIZATION LAYER

Docket No.: 303.085US4
Filed: August 31, 2000
Examiner: Renee Berry

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Group Art Unit: 2818

Commissioner for Patents
Washington, D.C. 20231

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Atty: Marvin L. Beekman
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